

Semiconductor Packaging and Assembly Equipment Market - Forecasts from 2017 to 2022

<https://marketpublishers.com/r/S73A5B1A510EN.html>

Date: October 2017

Pages: 81

Price: US\$ 3,600.00 (Single User License)

ID: S73A5B1A510EN

Abstracts

The global semiconductor packaging and assembly equipment market is projected to witness the growth at a CAGR of 7.30% during the forecast period to reach a total market size of US\$4.428 billion by 2022, increasing from US\$3.113 billion in 2017. The greater use of application of semiconductor integrated chips across the sphere is boosting the growth of this market. The ever changing market demanding multiple functions that can be performed by semiconductor integrated chips is on a rise. In addition, the rising number of mergers and acquisitions taking place in the market, increasing adoption of semiconductor integrated chips in automobiles, and rising technological developments in the semiconductor industry are the current market trends that are boosting the demand for semiconductor and assembly equipment globally throughout the forecast period.

By Type

The die bonding equipment is projected to increase significantly during the forecast period on account of increasing demand for semiconductor integrated chips. The rise in sales of both mobile and consumer electronic devices fuels the growth of the semiconductor market. Additionally, emerging technologies such as internet of things, machine to machine, ultra-high definition televisions, hybrid laptops, and vehicle automation further propel the demand for semiconductor integrated chips. This, in turn, will increase the requirement for packaging and assembly equipment, fuelling market growth. One of the latest trends that are gaining traction in the die bonding segment is the automation in automobiles. The utilization of different types of semiconductor integrated chips for various functions such as airbag control, automatic braking system, global positioning system(GPS), power doors and windows, car navigation and display, and automated driving will propel the need for innovative, power-saving, and reliant

semiconductor devices, which will in turn, create the need for advanced packaging techniques such as die bonders.

By Geography

Geographically, Asia Pacific is projected to dominate the global semiconductor packaging and assembly equipment market due to the presence of major players in the region. The Internet of things is expected to play a significant role in fuelling the semiconductor assembly and equipment market. Asia Pacific has access to abundant local cost-effective hardware and software, and less legacy technology to shed. By mirroring internet of things projects successfully piloted in Europe and beyond, and capitalizing on the cheap technology available, Asia Pacific has the potential to become the region with the most industrial and enterprise internet of things use cases and along the way, it will boost the semiconductor assembly and equipment market in the region.

Competitive Landscape

The global semiconductor packaging and assembly equipment market is competitive owing to the presence of well diversified international, regional and local players. However, some big international players dominate the market share owing to their brand image and market reach. The high market growth and favorable government policies are further attracting more players in the market while enhancing the competitive rivalry. The competitive landscape details strategies, products, and investments being done by key players in different technologies and companies to boost their market presence.

Some of the major players discussed in the report are Amkor Technologies, Inc., Toshiba Corporation, Qualcomm Technologies, Inc., Disco Corporation, Rudolph Technologies, Inc, ChipMOS Technologies, Inc., Powertech Technologies, Inc., Renesas Electronics Corporation.

Segmentation

The global semiconductor packaging and assembly equipment market has been segmented by type, application, and geography.

By Type

Plating Equipment

Inspection and Dicing Equipment

Wire Bonding Equipment
Die Bonding Equipment
By Application
Consumer Electronics
Healthcare Devices
Automotive Application
Enterprise Storage
Industrial Application
By Geography
North America
Europe
Middle East and Africa
Asia Pacific
South America

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